Dated: 27.03.18

## Sub: Information to Bidder for the procurement of Hardware Security Module (HSM)

## Ref: GeM Bid No. GEM/2018/B/50373 dt. 05.03.2018

| SN<br>No. | Details of Para<br>with Page No.<br>of Terms &<br>Conditions | Description of the matter in the Terms & Conditions  | Now to be read as  |
|-----------|--|--|--|
| 1         | Para-7 of Page<br>No. 1                                      | Delivery period: 30 days from the date of PO.  | Delivery period: <b>45 days</b> from the date of PO.   |
| 2         | Para-16.1 of<br>Page No. 4                                   | The supplier will have to supply the material within 30 days of issue of confirmed LOA/PO.   | The supplier will have to supply the material within <b>45 days</b> of issue of confirmed LOA/PO.  |
| 3         | Para-17 of Page<br>No. 4                                     | The bidder is required to submit the following documents offline to RailTel Corporation of India Ltd, Institutional Area Plot 143, Sector 44, Gurgaon before 15:00 Hrs of 02.04.2018 in a Sealed Envelope. The envelope shall bear 'DO NOT OPEN BEFORE' (due date & time as per GeM Portal). The offline documents shall be opened at 15:30 Hrs of 02.04.2018. In case the bidding is completed in the odd hours then the documents will be opened on next working day at 11:00 hours. Bids without these off line submission of documents will be summarily rejected. | The bidder is required to submit the following documents offline to RailTel Corporation of India Ltd, Institutional Area Plot 143, Sector 44, Gurgaon before 15:00 Hrs of 05.04.2018 in a Sealed Envelope. The envelope shall bear 'DO NOT OPEN BEFORE' (due date & time as per GeM Portal). The offline documents shall be opened at 15:30 Hrs of 05.04.2018. In case the bidding is completed in the odd hours then the documents will be opened on next working day at 11:00 hours. Bids without these off line submission of documents will be summarily rejected. |
|           | la.  | i. EMD   | i. EMD   |
|           |  | ii. MAF/ OEM Authorization Letter  | ii. MAF/ OEM Authorization Letter  |
|           |  | iii. BOQ of offered equipment.   | iii. BOQ of offered equipment.   |
|           | 2 2  | iv. Data Sheet of offered equipment.   | iv. Data Sheet of offered equipment.   |
|           |  | v. Financial and technical Eligibility<br>Criteria documents.  | v. Financial and technical Eligibility Criteria documents.   |
|           |  | vi. Technical Compliance of Specification as per Annex-I.  | vi. Technical Compliance of Specification as per Annex-I.  |
|           |  |  |  |

(Jagdeep Singh)

**Executive Director/Operations**